Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	100	V
Collector-Emitter Voltage	V_{CEO}	80	V
Emitter-Base Voltage	V_{EBO}	7	V
Continuous Collector Current	I_C	1	A
Peak Pulse Collector Current	I_{CM}	2	
Continuous Base Current	I_B	100	mA
Peak Pulse Base Current	I_{BM}	200	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

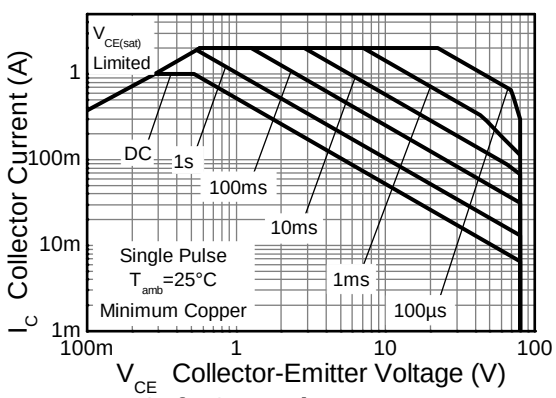
Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 5)	P_D	520	mW
Thermal Resistance, Junction to Ambient	(Note 5)	$R_{\theta JA}$	240	°C /W
Thermal Resistance, Junction to Leads	(Note 6)	$R_{\theta JL}$	20	°C/W
Operating and Storage Temperature Range		T_J, T_{STG}	-65 to +150	°C

ESD Ratings (Note 7)

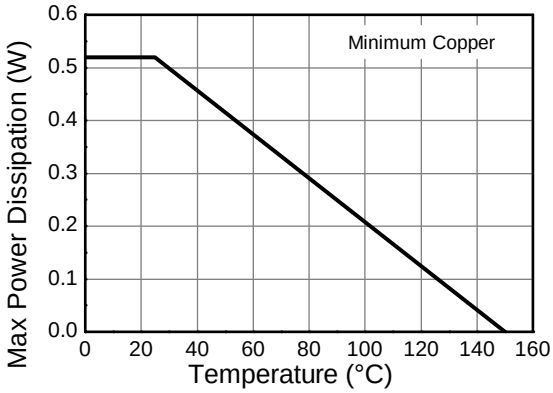
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes:
5. For a device mounted on minimum recommended pad layout FR4 PCB single sided 1oz copper; device is measured under still air conditions while operating at a steady-state.
6. Thermal resistance from junction to solder-point (at the end of the collector lead).
7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

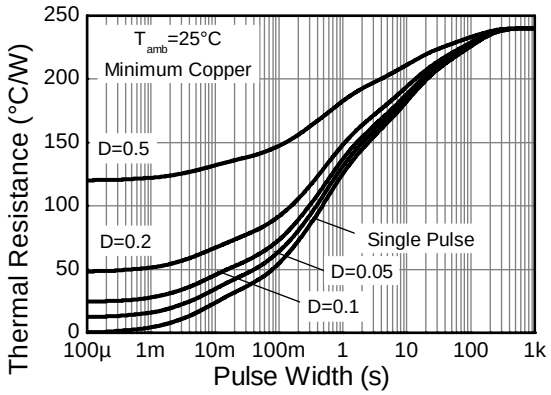
Thermal Characteristics and Derating Information



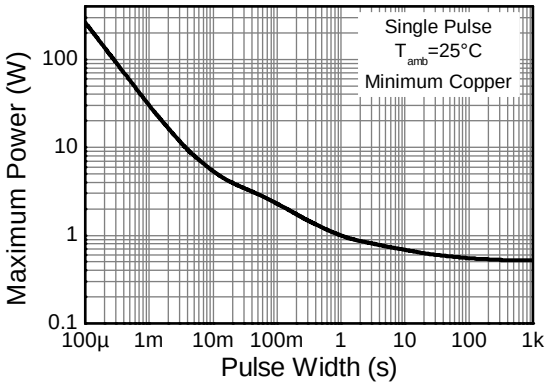
Safe Operating Area



Derating Curve



Transient Thermal Impedance



Pulse Power Dissipation

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	100	-	-	V	I_C = 100µA
Collector-Emitter Breakdown Voltage (Note 8)	BV_{CEO}	80	-	-	V	I_C = 10mA
Emitter-Base Breakdown Voltage	BV_{EBO}	7	-	-	V	I_E = 100µA
Collector Cut-off Current	I_{CBO}	-	-	0.1 20	µA	V_{CB} = 30V V_{CB} = 30V, T_A = +150°C
Emitter Cut-off Current	I_{EBO}	-	-	20	nA	V_{EB} = 4V
Static Forward Current Transfer Ratio (Note 8)	h_{FE}	25 100 25	- - -	- 250 -	-	I_C = 5mA, V_{CE} = 2V I_C = 150mA, V_{CE} = 2V I_C = 500mA, V_{CE} = 2V
Collector-Emitter Saturation Voltage (Note 8)	$V_{CE(sat)}$	-	-	0.5	V	I_C = 500mA, I_B = 50mA
Base-Emitter Turn-On Voltage (Note 8)	$V_{BE(on)}$	-	-	1.0	V	I_C = 500mA, V_{CE} = 2V
Transition Frequency	f_T	-	125	-	MHz	I_C = 50mA, V_{CE} = 10V f = 100MHz
Output Capacitance	C_{obo}	-	-	25	pF	V_{CB} = 10V, f = 1MHz

Note: 8. Measured under pulsed conditions. Pulse width ≤ 300µs. Duty cycle ≤ 2%.

Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

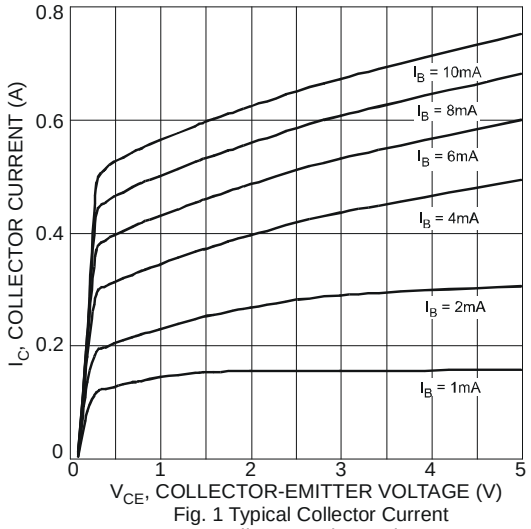


Fig. 1 Typical Collector Current vs. Collector-Emitter Voltage

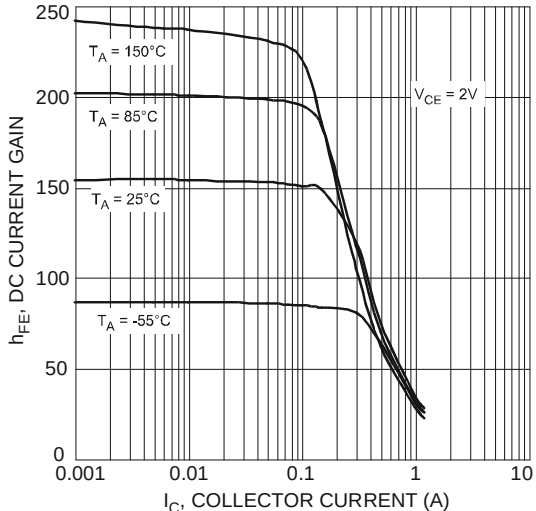


Fig. 2 Typical DC Current Gain vs. Collector Current

Typical Electrical Characteristics (continued)

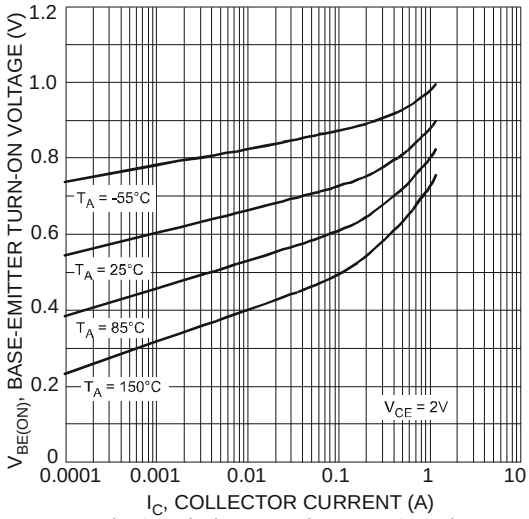


Fig. 3 Typical Base-Emitter Turn-On Voltage vs. Collector Current

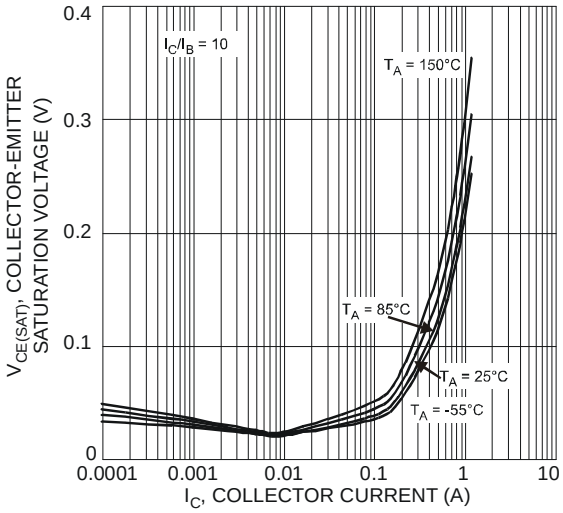


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

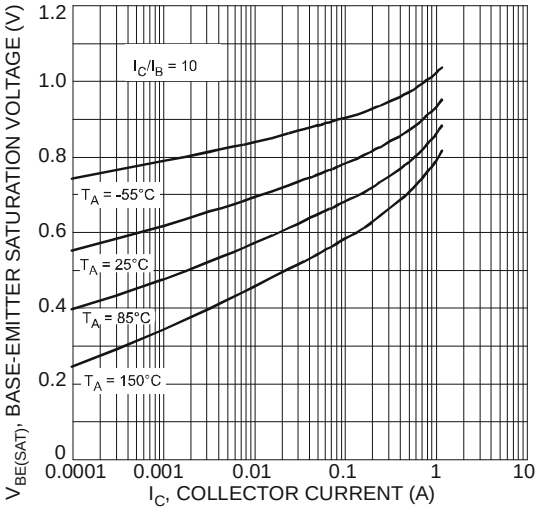


Fig. 5 Typical Base-Emitter Saturation Voltage vs. Collector Current

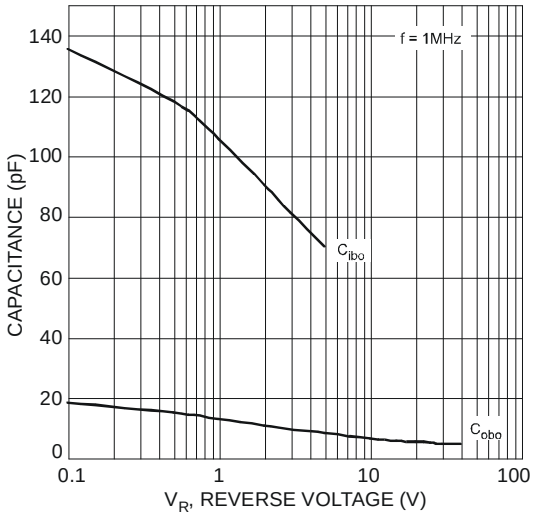
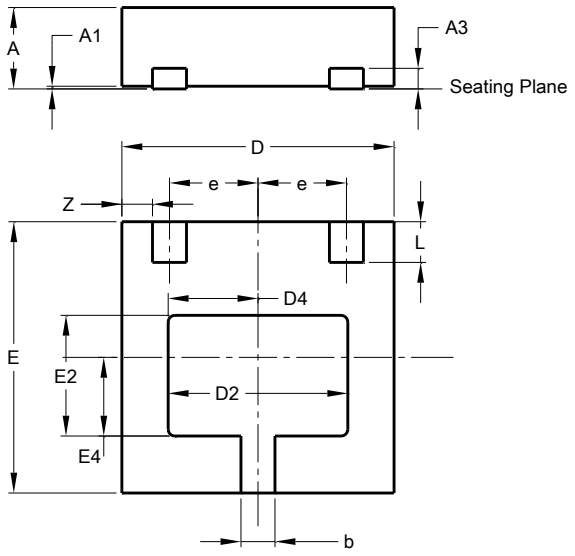


Fig. 6 Typical Capacitance Characteristics

Package Outline Dimensions

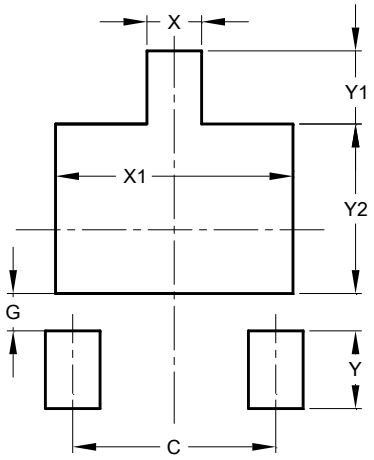
Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



U-DFN2020-3 (Type B)			
Dim	**Min**	**Max**	**Typ**
A	0.57	0.63	0.60
A1	0.00	0.05	0.02
A3	—	—	0.152
b	0.20	0.30	0.25
D	1.950	2.075	2.00
D2	1.22	1.42	1.32
D4	0.56	0.76	0.66
E	1.950	2.075	2.00
E2	0.79	0.99	0.89
E4	0.48	0.68	0.58
e	—	—	0.65
L	0.25	0.35	0.30
Z	—	—	0.225
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	1.300
G	0.240
X	0.350
X1	1.520
X2	1.700
Y	0.500
Y1	0.470
Y2	1.090

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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